

**Specification of the service:**

Overall Board size: 178x228 mm

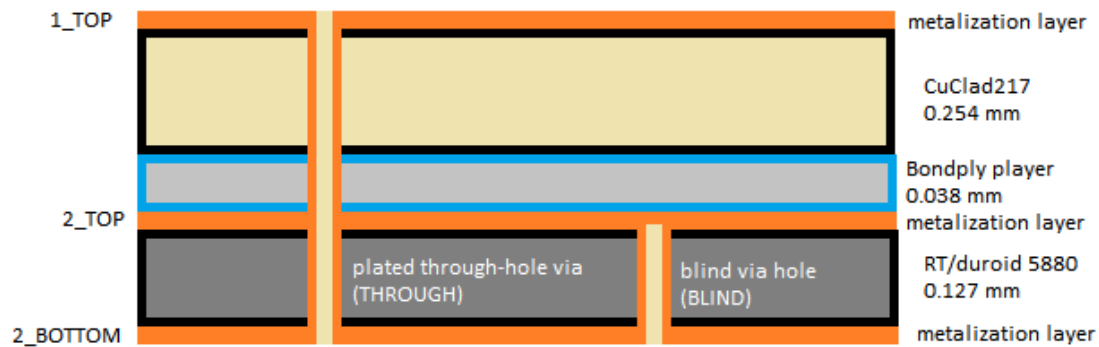
Multilayer board stackup:

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Copper	18 um
CuClad217	254 um
Bondply layer (RO2929)	~38 um
Copper	18 um
RT/duroid 5880	127 um
Copper	18 um

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Visualization of board stackup:



- 3 metallization layers,
- Substrate materials (CuClad217, RT/duroid 5880) provided by customer
- Finish: bare copper, no soldermask or any finish applied to boards
- Plated via-holes:
  - 2644 holes, 0.3 mm diameter (blind vias)
  - 20 holes, 2 mm diameter (through vias)
- Additional Milling - required, to cut the panel into 36 separate boards
- Lead time – 10 days